

ABSTRACT OF THE DISCLOSURE

IMPRINTED INTEGRATED CIRCUIT SUBSTRATE AND METHOD FOR IMPRINTING AN INTEGRATED CIRCUIT SUBSTRATE

5 A die-attach method and assembly using film and epoxy bonds speeds manufacturing for large die assemblies while providing improved bond characteristics. An adhesive film defining an epoxy flow mask is attached to the die or substrate, epoxy is dispensed within the epoxy flow mask area and the die is then bonded to the substrate. The film controls the flow of the epoxy, preventing spillover. Additionally, the epoxy area can be made small with respect to the die size, reducing the time required to dispense the epoxy and reducing the amount of epoxy material required.

10

15

20

25

30

35

40

45

50

55

60

65

70

75

80

85

90

95

100